



Material Content Data Sheet



Sales Product Name	TLE7270-2E			Issued	19. January 2018			
MA#	MA001680294							
Package	PG-SSOP-14-2			Weight*	83.15 mg			
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	1.717	2.06	2.06	20645	20645
leadframe	inorganic material	phosphorus	7723-14-0	0.009	0.01		104	
	non noble metal	zinc	7440-66-6	0.034	0.04		414	
	non noble metal	iron	7439-89-6	0.689	0.83		8287	
wire	non noble metal	copper	7440-50-8	27.978	33.65	34.53	336472	345277
	noble metal	gold	7440-57-5	0.136	0.16	0.16	1632	1632
	encapsulation	organic material	carbon black	1333-86-4	0.099	0.12		1196
encapsulation	plastics	epoxy resin	-	4.573	5.50		54996	
	inorganic material	silicondioxide	60676-86-0	45.034	54.17	59.79	541596	597788
leadfinish	non noble metal	tin	7440-31-5	0.976	1.17	1.17	11739	11739
plating	noble metal	silver	7440-22-4	0.768	0.92	0.92	9232	9232
glue	plastics	epoxy resin	-	0.285	0.34		3422	
	noble metal	silver	7440-22-4	0.854	1.03	1.37	10265	13687
*deviation	< 10%			Sum in total:		100.00		1000000

Important Remarks:

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This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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